

PRESSURIZED LIQUID DELIVERY MODULE

ABSTRACT OF THE DISCLOSURE

5 A pressurized delivery module having two chambers enables refill of the
module while liquid material continues to be supplied to a semiconductor processing
tool. Initially, the chambers are in fluid communication with each other through a
valve assembly, with positive pressure applied to the module from an inert gas supply.
When material in the module becomes depleted, the chambers are isolated from one
another to permit refilling. In the refill module state, one chamber remains pressurized,
10 with material remaining therein continued to be dispensed to the semiconductor
fabrication tool. The second chamber is vented and placed into fluid communication
with the bulk material supply. Once the level of material in the second chamber has
been replenished and processing of the remaining wafer has been completed, during
transfer of the next incoming wafer to the tool, the second chamber is sealed off from
15 the material supply, repressurized, and placed back into fluid communication with the
first chamber.

PA 3097181 v1